

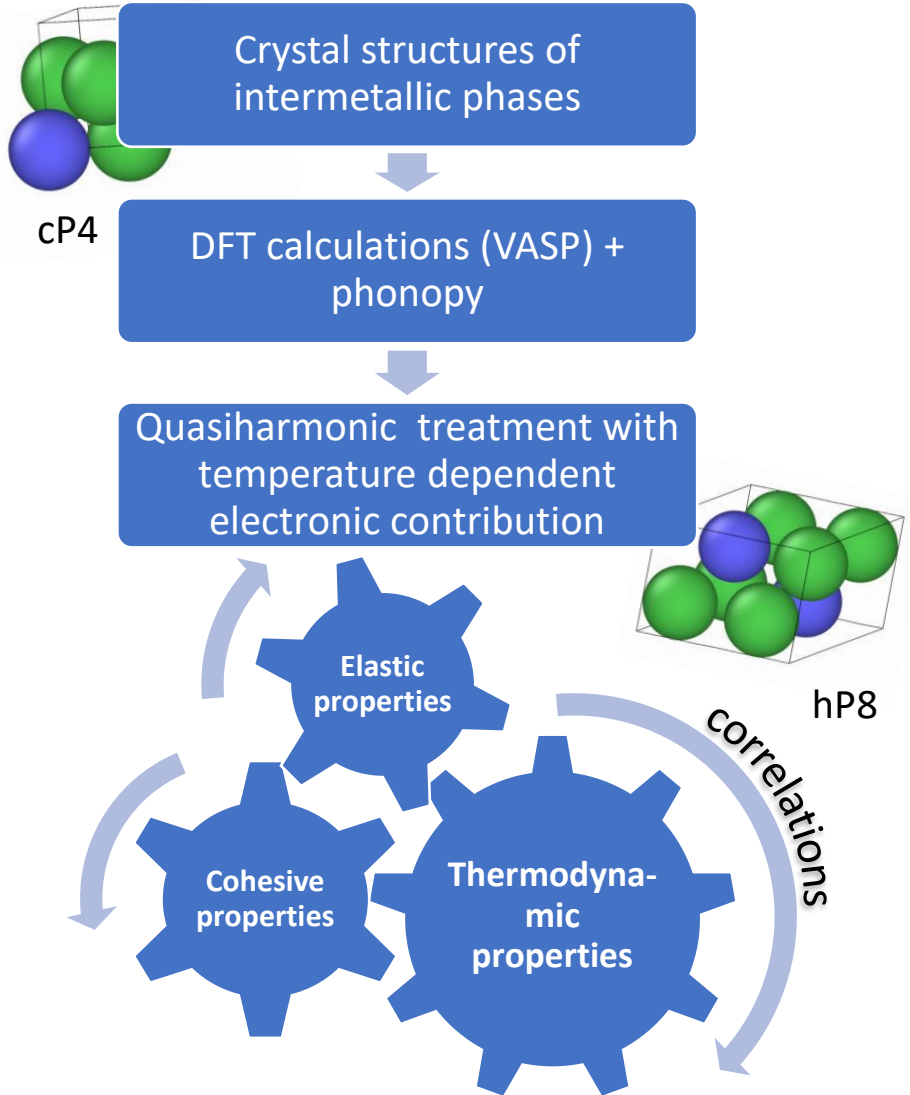
Ab initio study of thermophysical and mechanical properties of Ni-X (X=In,Sn) intermetallic compounds

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Motivation

- Intermetallic compounds (ICs) of the Ni-In and Ni-Sn systems in relation to the In-Sn solder alloys and their use in lead free micro-soldering processes, with Ni as the contact material.

Objetives

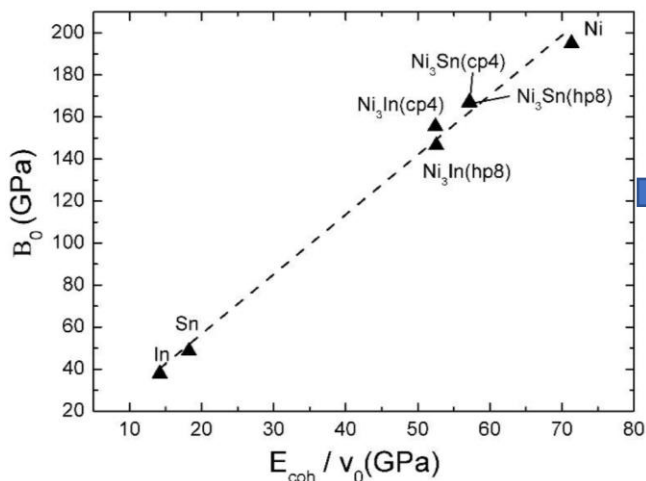
- Extend previous T = 0 K ab initio database [Bertoldi et al., JPED 2017] to include thermal properties.
- Characterize the cohesive, elastic and thermodynamic properties of the Ni₃X (X =In,Sn) compounds, for the low temperature hP8 stable phase, and the cP4 phase, present at high pressure.
- Establish interrelations and correlations between cohesive, elastic and vibrational properties.

Methodology

- DFT-PAW-GGA (XC:PW91) calculations + quasi-harmonic approximation (QHA) to predict: VDOS, Debye temperatures, Gibbs energy and heat capacities.
- Include temperature dependent electronic contribution to the free energy.
- Codes: VASP [Kresse et al., Comput. Mat. Science, 1996] and PHONOPY [Togo et al. PRB, 2008]

Zero-Kelvin calculations

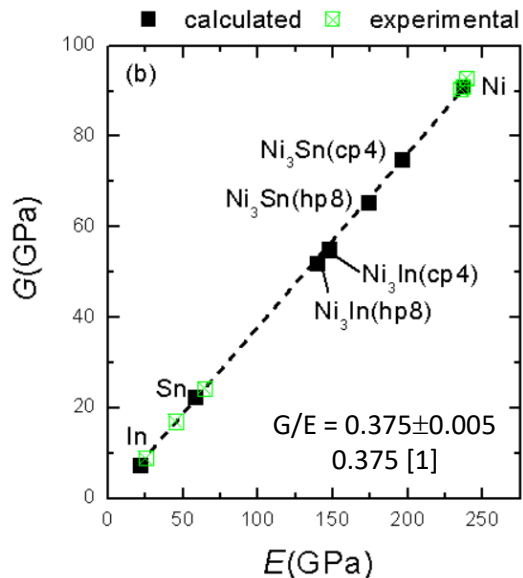
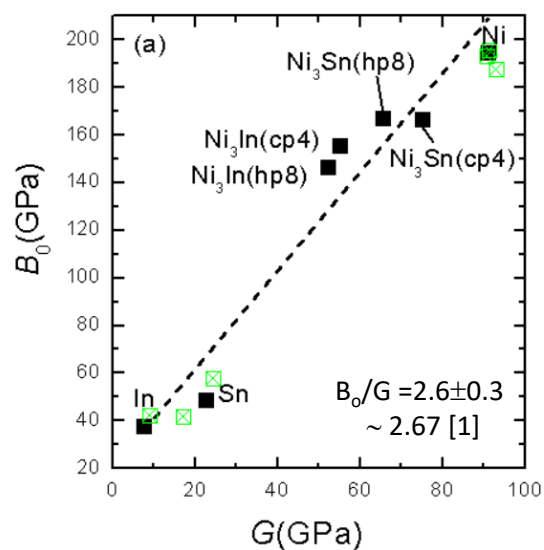
Energy and elastic modulus



Isothermal bulk modulus (B_0) vs cohesive energy density (E_{coh}/v_0) for the elemental solids and the Ni_3X compounds.

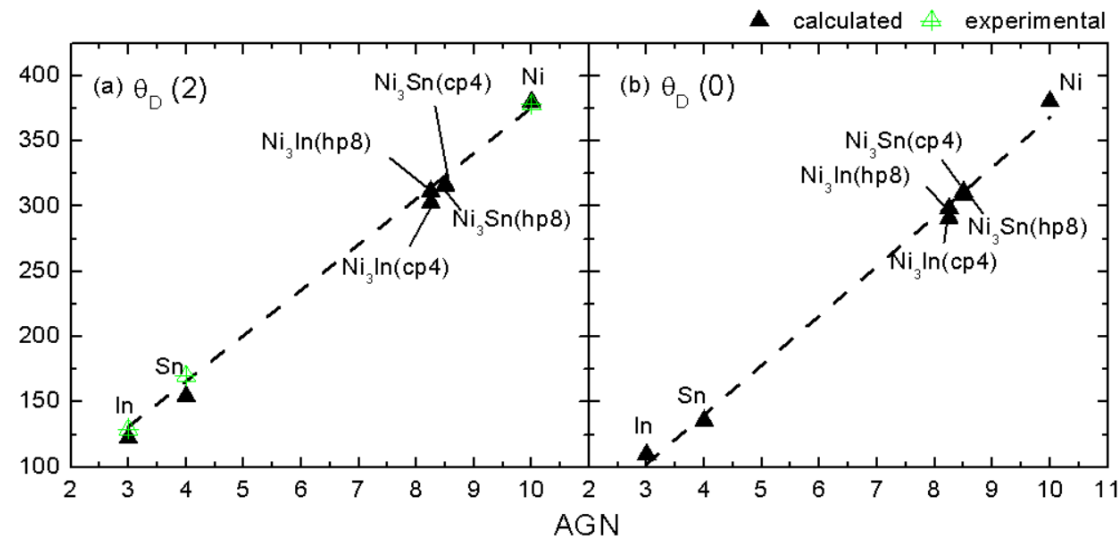
Bertoldi *et al.*, Calphad 71, (2020)

Correlations: B_0 , shear (G) and Young (E) modulus



[1] Köster and Franz, Metal. Rev., (1961)

Debye temperatures



Debye temperatures $\theta_D(2)$ and $\theta_D(0)$ (in K) as functions of the average group number (AGN):

$$\theta_D(0) = \frac{\hbar}{k_B} e^{1/3} \cdot \exp \left[\frac{\int_0^{\omega_{max}} \ln \omega D(\omega) d\omega}{\int_0^{\omega_{max}} D(\omega) d\omega} \right]$$

$$\theta_D(2) = \frac{\hbar}{k_B} \left[\frac{5}{3} \frac{\int_0^{\omega_{max}} \omega^2 D(\omega) d\omega}{\int_0^{\omega_{max}} D(\omega) d\omega} \right]^{1/2}$$

AGN: weighted average of the number of valence electrons for the elements Ni, In and Sn: Ni($3d^8 4s^2$), In ($5s^2 5p^1$), Sn ($5s^2 5p^2$).

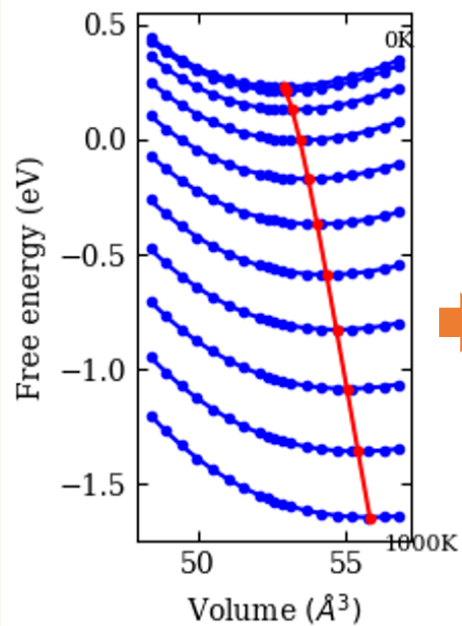
High temperature calculations

$$F = F^{vib}(T, V) + F^{el}(T, V)$$

Vibrational contribution
Electronic contribution

$$F^{vib}(T, V) = \frac{1}{2} \sum_{q,j} \overset{\text{QHA}}{\hbar \omega_{q,j}(V)} + k_B T \sum_{q,j} \ln(1 - e^{-\overset{\text{QHA}}{\hbar \omega_{q,j}(V)/k_B T}})$$

$$F^{el}(T, V) = \sum_j f_j(\epsilon_j(V), T) \epsilon_j(V) + k_B T \sum_j \left[f_j(\epsilon_j(V), T) \ln(f_j(\epsilon_j(V), T)) + (1 - f_j(\epsilon_j(V), T)) \ln(1 - f_j(\epsilon_j(V), T)) \right]$$



$\epsilon_j(V)$: 1-electron eigenvalues of the KS equations

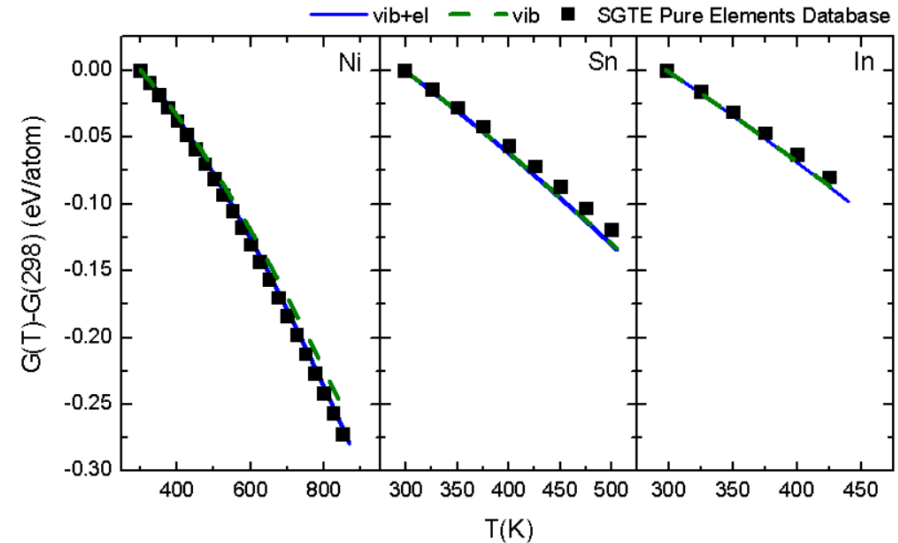
$f_j(\epsilon_j, T)$: Fermi-Dirac occupation function in thermal equilibrium at temperature T

$$G(T, P) = \min_V [F(T, V) + PV]$$

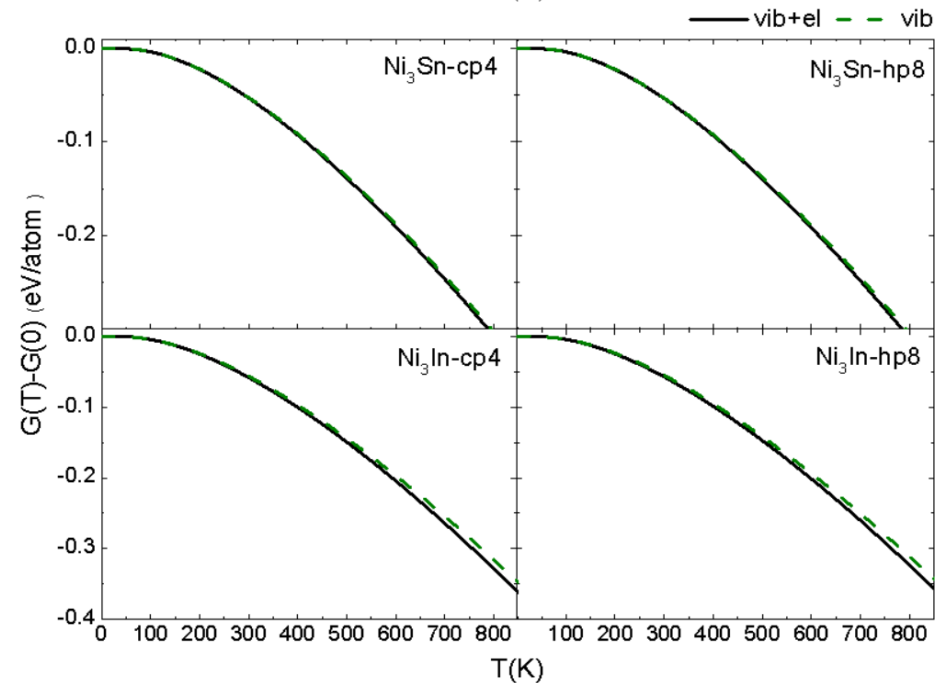
$$C_p(T, P) = -T \frac{\partial^2 G(T, P)}{\partial T^2}$$

Guillan, J. Phys.: Cond. Matter **1** 689, (1989)

Gibbs energy



Temperature dependence of the Gibbs energy (G) for the pure elements, with and without electronic (el) contribution. SGTE Pure Elements Database: Dinsdale, Calphad, (1991)

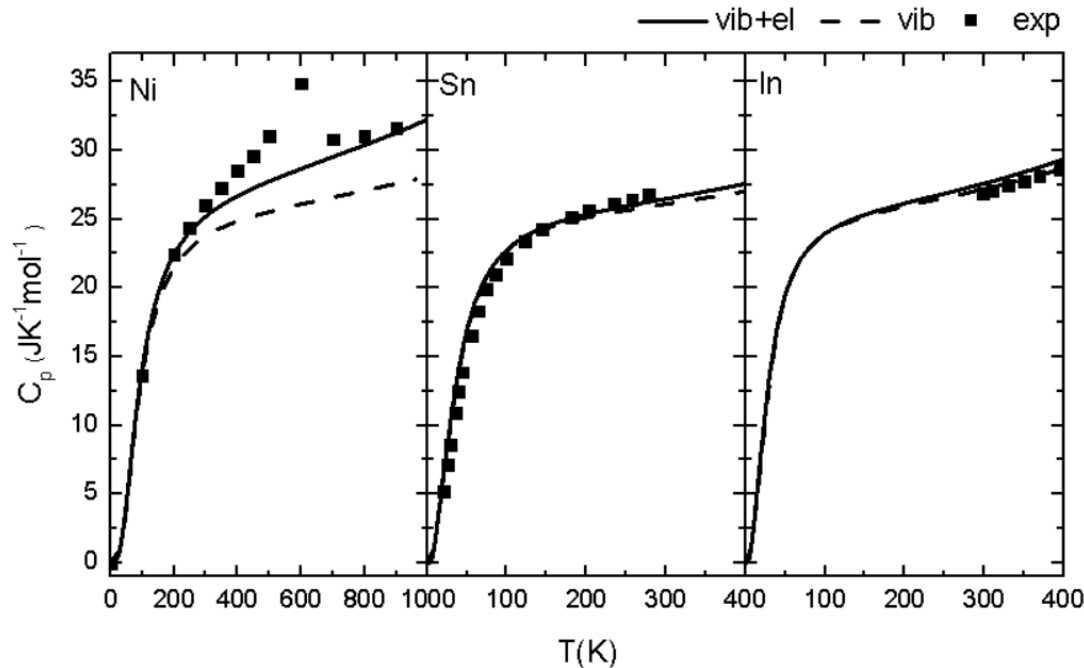


Temperature dependence of the Gibbs energy for the Ni₃X compounds, with and without electronic contribution.

Heat capacity

Heat capacity (C_p) at $P=0$ for the pure elements, with and without the temperature dependent electronic free energy contribution.

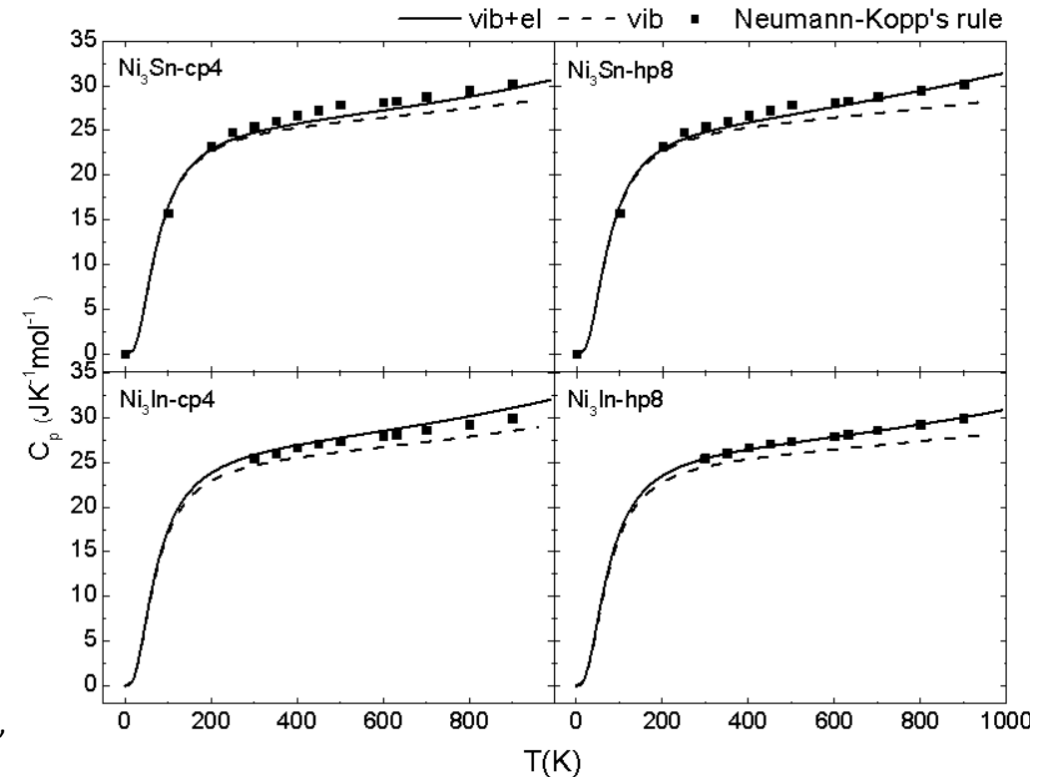
Experimental data: Ni [1], Sn [2], In [3]



[1] Chase Jr, M., J. Phys. Chem. Ref. Data, Monograph 9 (1998), [2] Khvan, A. V. et al., Calphad 65 (2019), [3] Grønvoold F., J. Therm. Anal. Calorim. 13 (1978)

Heat capacity at $P=0$ for the Ni_3X compounds in comparison with values obtained with Neumann-Kopp's rule and the pure elements

$$SGTE \text{ results: } C_p = \sum_{i=1}^N X_i \cdot C_{p,i}$$



Conclusions

- For the elements and the Ni_3X ($X=In,Sn$) ICs linear correlations have been established: (i) between the B_0 and E_{coh}/V_0 , and (ii) between EEMs: B_0 vs G , and for G vs E .
- The inclusion of a temperature dependent electronic free energy contribution in general improves the agreement with the experimental data of the thermal properties evaluated in the QHA.
- For the compounds the results obtained for C_p agree with Neumann-Kopp's rule.